

ABSTRACT

METHOD OF FABRICATING ELECTRONIC DEVICE EMPLOYING A FLAT
FLEXIBLE CIRCUIT AND INCLUDING THE DEVICE ITSELF

5 A method of fabricating an electronic device
(80), along with the product of that method is disclosed.
A flat flexible dielectric substrate (68) is provided with
a generally round hole (72) of a given diameter and with a
ductile conductive film (70) on the substrate in an area at
least about the hole. A generally round terminal pin (74)
10 is provided with a given diameter greater than that of the
hole. The difference between the diameter of the pin (74)
and the diameter of the hole (72) is on the order of 5% to
50% of the diameter of the hole. At least a portion of the
pin (74) is coated with a non-conductive adhesive (82).
15 The pin (74) is inserted into the hole (72) in the
substrate (68) such that the non-conductive adhesive (82)
is scraped longitudinally from the pin to an area about the
hole and the pin, leaving the pin (74) in contact with the
conductive film (70).

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